



- 1449

SHEET 1 OF 1

INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)					ATTY. DOCKET NO.		SERIAL NO.	
					2002B131/2		10/681,470	
					APPLICANT			
					Van den Bossche, et al.			
FILING DATE					GROUP			
October 8, 2003					Not Yet Assigned			
U.S. PATENT DOCUMENTS								
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
KE	AA	3,625,727	12/07/71	Lightfoot et al.	117	6		
	AB	4,452,835	06/05/84	Vasudevan	428	35		
	AC	4,497,941	02/05/85	Aliani et al.	526	331		
	AD	5,362,792	11/08/94	Maayeh	524	491		
KE	AE	6,376,095	04/23/02	Cheung et al.	428	516		
	AF							
	AG							
	AH							
	AI							
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	PUBL DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KE	AJ	EP0369705	05/23/90	Europe	B32B	27/32		
	AK	EP0078122	05/04/83	Europe	C08F	210/02		
	AL	GB1377206	12/11/74	Great Britain	C08F	37/00		
	AM	GB2138008	10/17/84	Great Britain	C08L	23/08		
	AN	JP09227840	09/02/97	Japan	C09J	7/02	✓	
	AO	JP58-47038	03/18/83	Japan	C08L	23/08		✓
KE	AP	JP51114480	10/08/76	Japan	B32B	31/30		✓
OTHER DISCLOSURES (Including Author, Title, Date, Pertinent Pages of Publication, Etc.)								
KE	AQ	Abstract for JP58-47038 (March 18, 1983)						
KE	AR	Abstract for JP51114480 (October 8, 1976)						
EXAMINER /Kelechi Egwim/					DATE CONSIDERED 05/01/2006			
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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
KE	AA	3,558,399	01/26/71	Turner	156	308	
	AB	3,778,398	12/11/73	Mestetsky	260	28.5 R	
	AC	3,819,581	06/25/74	Smith	260	47 EN	
	AD	3,926,878	12/16/75	Shimizu et al.	260	27 EV	
	AE	3,933,691	01/20/76	Lindemann	260	2.5 L	
	AF	4,001,158	01/04/77	Lindemann	260	29.6 TA	
	AG	4,010,130	03/01/77	Matsuo et al.	260	28.5 AV	
	AH	4,020,228	04/26/77	Eastes	428	347	
	AI	4,022,850	05/10/77	Booth et al.	260	897 B	
KE	AJ	4,048,378	09/13/77	Pelzek	428	483	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	PUBL. DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KE	AK	CA 1 011 034	05/24/77	Canada	402	263		
	AL	EP 0 078 122 B1	01/25/89	Europe	C08F	210/02		
	AM	EP 0 147 088 B1	05/30/90	Europe	B32B	7/04		
	AN	EP 0 188 901 B1	06/12/91	Europe	C09J	131/04		
KE	AO	EP 0 247 896 B1	06/19/91	Europe	B32B	27/32		

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KE	AA	4,127,619	11/28/78	Godfrey	260	889	
	AB	4,256,622	03/17/81	Smith	260	33.2 R	
	AC	4,287,034	09/01/81	Pieslak et al.	204	147	
	AD	4,337,284	06/29/82	Cooper et al.	428	35	
	AE	4,351,928	09/28/82	Smith	525	443	
	AF	4,362,784	12/07/82	Kato et al.	428	340	
	AG	4,366,662	01/04/83	Katsura et al.	53	478	
	AH	4,476,896	10/16/84	Schirmer	137	561A	
	AI	4,477,501	10/16/84	Kojima et al.	428	35	
KE	AJ	4,585,682	04/29/86	Colarusso et al.	428	57	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	PUBL. DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KE	AK	EP 0 247 898 B1	11/22/90	Europe	B32B	27/32		
	AL	EP 0 263 882 B1	10/23/91	Europe	B32B	27/32		
	AM	EP 0 281 694 A1	09/14/88	Europe	B64D	11/06		
	AN	EP 0 299 844 B1	05/26/93	Europe	G02C	7/16		X
	AO	EP 0 299 884 B1	12/04/91	Europe	C09J	7/02		X
KE	AP	EP 0 301 867 A2/3 /Kelechi Egwim/	02/01/89	Europe	C09J	36/14 05/01/2006		

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KE	AA	4,613,632	09/23/86	Aliani et al.	523	172		
	AB	4,632,784	12/30/86	Baggiolini et al.	260	397.2		
	AC	4,670,349	06/02/87	Nakagawa et al.	428	516		
	AD	4,710,190	12/01/87	Wood et al.	604	389		
	AE	4,731,282	03/15/88	Tsukagoshi et al.	428	220		
	AF	4,741,957	05/03/88	Park	428	349		
	AG	4,801,485	01/31/89	Sallee et al.	428	198		
	AH	4,846,827	07/11/89	Sallee et al.	604	385.2		
	AI	4,852,754	08/01/89	Holdsworth et al.	215	347		
KE	AJ	4,921,749	05/01/90	Bossaert et al.	428	216		
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	PUBL. DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KE	AK	EP 0 340 990 A2	11/08/89	Europe	C09J	3/14		
	AL	EP 0 353 224 B1	01/16/91	Europe	C08F	289/00		
	AM	EP 0 369 705 A2	05/23/90	Europe	B32B	27/32		
	AN	EP 0 424 761 B1	07/27/94	Europe	B32B	27/32		X
KE	AO	EP 0 592 913 B1	04/20/94	Europe	C09J	7/00		X
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U.S. PATENT DOCUMENTS								
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
KE	AA	4,981,734	01/01/91	Akao et al.	428	35.9		
	AB	4,988,467	01/29/91	Holdsworth et al.	264	46.6		
	AC	5,024,887	06/18/91	Yamane	428	335		
	AD	5,075,156	12/24/91	Tanaka et al.	428	212		
	AE	5,100,721	03/31/92	Akao	428	218		
	AF	5,128,397	07/07/92	Horseley et al.	524	290		
	AG	5,141,809	08/25/92	Arvedson et al.	428	349		
	AH	5,154,981	10/13/92	Brant et al.	428	520		
	AI	5,178,960	01/12/93	Cook	428	461		
	AJ	5,183,706	02/02/93	Bekele	428	349		
KE	AK	5,215,809	06/01/93	Hoso et al.	428	193		
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	PUBL. DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KE	AL	EP 0 608 175 B1	11/03/99	Europe	C09J	7/02		X
	AM	EP 0 622 430 B2	11/02/94	Europe	C09D	123/08		X
	AN	EP 0 679 685 B1	09/16/98	Europe	C08L	23/08		
	AO	EP 0 761 315 B1	03/12/97	Europe	B05B	15/04		X
KE	AP	EP 0 826 754 A2/3	03/04/98	Europe	C09J	7/02		X
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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
KE	AA	5,217,812	06/08/93	Lee	428	461	
	AB	5,300,353	04/05/94	Yoshimura et al.	428	213	
	AC	5,340,649	08/23/94	Roeker et al.	428	344	
	AD	5,373,049	12/13/94	Ornstein et al.	524	487	
	AE	5,512,124	04/30/96	Hansen	156	334	
	AF	5,530,065	06/25/96	Farley et al.	525	240	
	AG	5,541,246	07/30/96	Dandreaux et al.	524	272	
	AH	5,643,676	07/01/97	Dobashi et al.	428	411.1	
	AI	5,703,153	12/30/97	Maayeh	524	499	
KE	AJ	5,766,714	06/16/98	Profetto et al.	428	40.1	

FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	PUBL. DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KE	AK	EP 0 827 526 B1	08/18/99	Europe	C09J	123/18		
	AL	FR 2 600 981 A3	01/08/88	France	B65D	65/40		X
	AM	FR 2 807 442 A1	10/12/01	France	C09J	131/04		X
	AN	FR 2 807 443 A1	10/12/01	France	C09J	131/04		X
KE	AO	GB 1 049 033	11/23/66	Great Britain	C08F	47/02		

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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
KE	AA	5,895,714	04/20/99	Malek	428	337		
	AB	6,017,998	01/25/00	Duan et al.	524	591		
	AC	6,060,425	05/09/00	Morohoshi et al.	503	200		
	AD	6,063,462	05/16/00	Tsukamoto et al.	428	36.7		
	AE	6,094,889	08/01/00	Van Loon et al.	53	450		
	AF	6,225,520	05/01/01	Bauduin et al.	602	52		
KE	AG	RE 34122 (reissue of US4,880,487)	11/10/92	Sheehan et al.	156	327		
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	PUBL. DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KE	AH	GB 1 401 880	08/06/75	Great Britain	C08J	5/18		
	AI	GB 2 138 008 A	10/17/84	Great Britain	C08L	23/08		
	AJ	GB 2 277 479 A	11/02/94	Great Britain	C09J	7/02		
	AK	WO 87/07216	12/03/87	PCT	B32B	27/32		
	AL	WO 91/06609	05/16/91	PCT	C09J	7/00		
KE	AM	WO 94/19414	09/01/94	PCT	C09D	5/00		
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							YES	NO
KE	AA	WO 98/37139	08/27/98	PCT	C08L	23/10		
	AB	WO 98/37140	08/27/98	PCT	C08L	23/16		
	AC	WO 98/37141	08/27/98	PCT	C08L	23/16		
	AD	WO 98/37142	08/27/98	PCT	C08L	23/16		
	AE	WO 98/37143	08/27/98	PCT	C08L	23/16		
	AF	WO 00/00657	02/10/00	PCT	C09F	1/00		
	AG	WO 00/78859	12/28/00	PCT	C08L	23/04		
	AH	WO 02/18510	08/28/01	PCT	C09J	123/08		
	AI	WO 02/36703	05/10/02	PCT	C09j	7/02		
	AJ	HEI 4(1992)239081	08/26/92	Japan	C09J	7/02	X	
KE	AK	JP 02222479	08/09/02	Japan	G08C	17/00	X	
OTHER DISCLOSURES (Including Author, Title, Date, Pertinent Pages of Publication, Etc.)								
KE	AL	Abstract, EP 0 299 844, "Visual intensity restrictor for cataract sufferers - scans field of view using electronic shutter so that instantaneous receipt of light is confined to small area of eye", (01/18/89)						
KE	AM	Abstract, EP 0 299 884, "Flexible self-adhesive film for temporary protection", (01/18/89)						
KE	AN	Abstract, EP 0 424 762, "High-gloss multilayer films and their hot lamination", (05/02/91)						
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OTHER DISCLOSURES (Including Author, Title, Date, Pertinent Pages of Publication, Etc.)			
KE	AA	Abstract, EP 0 592 913, "Films of copolymers of alpha-olefins and unsaturated polar monomers for protecting automobile surfaces", (04/20/94)	
	AB	Abstract, EP 0 608 175, "Pressure-sensitive adhesive-coated films for protection of surfaces of plastic moldings", (07/27/94)	
	AC	Abstract, EP 0 622,430 (DE 4 313 542), "Ethylene-vinyl acetate copolymer film for lamination of nonmetallic substrates", (11/02/94)	
	AD	Abstract, EP 0 761 315 (DE 1 953 2220), "Self-adhesive protective film", (03/06/97)	
	AE	Abstract, EP 0 826 754 (DE 1 963 5704), "Self-adhesive protective plastic film", (03/05/98)	
	AF	Abstract, FR 260 0981, "Flexible adhesive tape for temporary protection of fragile surfaces and manufacturing method", (01/08/88)	
	AG	Abstract, FR 280 7442, "Paraffin-free EVA-based hot-melt adhesive for fabricating thermo-sealable products in molds", (10/12/01)	
	AH	Abstract, FR 280 7443, "Paraffin-free EVA-based hot-melt adhesive for fabricating thermo-sealable products in molds", (10/12/01)	
	AI	Abstract ZA 6803092, "Extrusion-coating of ethylene-vinyl acetate copolymer coatings", B.W. Elliott, (11/12/68)	
	AJ	Abstract, BE 808488, "Self adhesive, transparent packaging film - consisting of mixture of ethylene/vinyl ester copolymer and hydrocarbon resin, polybutene or polyisobutene", (12/14/72)	
	AK	Abstract, DE 2549612, "Hydrocarbon resins", (11/05/75)	
	AL	Abstract, FR 1573940, "Adhesives for soil facing", (07/11/69)	
	AM	Abstract, EP 884173, "Oxygen-absorbing multilayer film and oxygen-absorbing packaging container therefrom with concealed deoxidizing agent discoloration", (06/12/98)	
	AN	Abstract, EP 830953, "Multilayered thermal-transfer medium from water-based formulation", (09/22/97)	
KE	AO	Abstract, EP 810087, "Heat-shrinkable multilayer films having excellent sealing properties for use as vacuum shrink packages and food packages", (05/28/97)	
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KE	AA	Abstract, EP 803559, "Hot-melt adhesive compositions containing ethylene- α -olefin copolymer and carboxylated polyethylene for packaging", (04/23/97)	
	AB	Abstract, EP 679685, "Ethylene copolymer composition for extruded sheet and film", (04/25/95)	
	AC	Abstract, EP 445955, "Ethylene polymer blends for heat sealable packaging films", (02/27/91)	
	AD	Abstract, EP 312288, "Manufacture of heat-sealable polyolefin films", (10/11/88)	
	AE	Abstract, EP 240253, "Resin Emulsions", (03/26/87)	
	AF	Abstract, EP 129310, "Sealing gaskets, and container closures incorporating them", (04/18/84)	
	AG	Abstract, JP 01113241, "Multilayer Sheet for Light-Weight Container", (05/01/89)	
	AH	Abstract, JP 0145775, "Peelable Surface Protective Film", (08/30/83)	
	AI	Abstract, JP 0198383, "Surface Protecting Film", (07/17/92)	
	AJ	Abstract, JP 02198841, "Heat-Sealing Cover Material", (08/07/90)	
	AK	Abstract, JP 03020382, "Hot-Melt Adhesive Composition", (01/29/91)	
	AL	Abstract, JP 04239080, "Self-adhesive tape and its manufacture", (08/26/92)	
	AM	Abstract, JP 04239081, "Surface Protective Film", (08/26/92)	
	AN	Abstract, JP 06345911, "Resin Composition for Print Laminate", (12/20/94)	
	AO	Abstract, JP 08060111, "Surface-Protective Film", (03/05/96)	
	AP	Abstract, JP 08325338, "Tackifying Agent for Ethylenic Copolymer and its Adhesive Composition", (12/10/96)	
KE	AQ	Abstract, JP 10158593, "Thermoplastic Film Resin", (06/16/98)	
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KE	AA	Abstract, JP 10219215, "Hot Melt Adhesive Composition", (08/18/98)	
	AB	Abstract, JP 11020097, "Sealing Film for Electronic Device", (01/26/99)	
	AC	Abstract, JP 2001 207145, "Hot-Melt Adhesive Composition", (07/31/01)	
	AD	Abstract, JP 54160482, "Coated polyethylene films for covering metals", (06/09/78)	
	AE	Abstract, JP 54046282, "Surface Protective Film", (04/12/79)	
	AF	Abstract, JP 50034048, "Ethylene-vinyl Acetate Copolymer Packaging Films, (07/26/73)	
	AG	Abstract, JP 50123139, "Resin Adhesives for Polyolefin Resins", (03/18/74)	
	AH	Abstract, JP 52015094, "Assembly and Transfer Apparatus of Ship Body Block", (02/04/77)	
	AI	Abstract, JP 53112983, "Laminated Film", (10/02/78)	
	AJ	Abstract, JP 54119535, "Heat-Active Adhesive Composition Capable of Extrusion Coating", (09/17/79)	
	AK	Abstract, JP 55084659, "Films for heat-seal", (12/22/78)	
	AL	Abstract, JP 56049264, "Heat-shrinkable laminated films", (09/27/79)	
	AM	Abstract, JP 57008234, "Heat-Sealable Resin Composition", (01/16/82)	
	AN	Abstract, JP 57158276, "Hot-Melt Adhesive Composition", (09/30/82)	
	AO	Abstract, JP 58015545, "Heat-Sealable Resin Composition", (01/28/83)	
	AP	Abstract, JP 61183371, "Heat-Sealable Resin Composition", (08/16/86)	
	AQ	Abstract, JP 62149775, "Hot-Melt Adhesive", (07/03/87)	
KE	AR	Abstract, JP 51114480, "A Method for Manufacturing a Laminate", (10/08/76)	
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	AB	Abstract, JP 53069792, "Easily Separable Material for Package", (06/21/78)	
	AC	Abstract, JP 58051130, "Polyethylene-coated Steel Pipe", (03/25/83)	
	AD	Abstract, JP 59050295, "Plastics coated tubes for e.g. underground pipelines - using compsn. Contg. Crosslinked and non-crosslinked polyolefin resins, colourant, carbon black UV absorber, antioxidant, etc." (08/31/88)	
	AE	Abstract, JP 63003743, "Vinyl copolymers for heat-sealable lids", (10/31/79)	
	AF	Abstract, JP 9207280, "Heat-Resistant Protective Film", (08/12/97)	
	AG	Abstract, JP Kokai (A) 2-222479, "Adhesive", (09/05/90)	
	AH	Abstract, JP Kokai (A) 54-160482, "Laminated Film", (12/19/79)	
	AI	Abstract, JP 2001081420, "Hot-tack pressure-sensitive adhesive sheets", (03/27/01)	
	AJ	Abstract, JP 2000052526, "Decorative sheets for furnitures and building interiors", (08/07/98)	
	AK	Abstract, JP 11138720, "Low-temperature sealable composite films with high heat seal strength and good hot tack properties", (11/11/97)	
	AL	Abstract, JP10120841, "Polyethylene-type resin compositions for extrusion lamination and their extruded laminates with improved heat sealability at low temperature", (10/18/96)	
	AM	Abstract, JP 09327888, "Paper laminates and their packagings for liquids", (06/11/96)	
	AN	Abstract, JP 09277449, "Thermosetting resin laminate decorative materials for furnitures and building materials and their manufacture", (04/16/96)	
	AO	Abstract, JP 08003384, "Ethyleneic resin compositions for food packaging films", (06/24/94)	
	AP	Abstract, JP 05043752, "Hot tack and heating sealing properties of EVOH", (08/09/91)	
KE	AQ	Abstract, JP 01268742, "Resin compositions for high-speed extrusion molding and method of laminating", (04/19/88)	
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		2002B131/2	10/681,470
		APPLICANT	
		Van den Bossche et al.	
		FILING DATE	GROUP
		October 8, 2003	Unassigned
OTHER DISCLOSURES (Including Author, Title, Date, Pertinent Pages of Publication, Etc.)			
KE	AA	Abstract, JP 60044540, "Linear low-density polyethylene resin compositions", (08/19/83)	
	AB	Abstract, JP 59179643, "Composition for extrusion molding", (03/31/83)	
	AC	Abstract, JP 59066437, "Resin compositions for films", (10/08/82)	
	AD	Abstract, JP 58037037, "Polyethylene blends with good extrusion processability", (08/28/81)	
	AE	Abstract, JP 58001558, "Laminated packaging films with good processability", (06/26/81)	
	AF	Abstract, JP 11070505, "Scratch-resistant decorative wood materials laminated with plastic composite films with good surface appearance and bendability and manufacture thereof", (05/21/98)	
	AG	Abstract, JP 10071660, "Hot-melt adhesives-containing disposable products with excellent water absorbing properties", (04/11/97)	
	AH	Abstract, JP 09104727, "Vinyl acetate-grafted hydrocarbon resins as tackifiers for hot-melt adhesives", (10/09/95)	
	AI	Abstract, JP 06345911, "Resin compositions for lamination on printed materials", (06/11/93)	
	AJ	Abstract, JP 05117628, "Moldable sealants for use in automobiles", (10/31/91)	
	AK	Abstract, JP 02150386, "Heat-sensitive transfer printing inks", (12/01/88)	
	AL	Abstract, JP 62263203, "Hydrocarbon resins as additives for adhesives", (05/12/86)	
	AM	Abstract, JP 62149775, "Hot-melt adhesives", (12/16/85)	
	AN	Abstract, JP 57158276, "Hot-melt adhesive compositions", (03/26/81)	
	AO	Abstract, JP 57008234, "Heat-sealable resin compositions", (06/17/80)	
	AP	Abstract, JP 56028257, "Hot-melt adhesive compositions", (08/15/79)	
KE	AQ	Abstract, JP 52015094, "Heat-sealable polyester film laminates", (07/30/73)	
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KE	AA	Abstract, JP 51114480, "Heat-sealable plastic laminates", (04/01/75)	
	AB	Abstract, JP 50119034, "Hot-melt adhesives", (03/05/74)	
	AC	Abstract, JP 61162539, "Modified polyolefin compsn. for adhesion - comprises ethylene-alpha-olefin random copolymer, tackifier and modified polyethylene", (09/22/93)	
	AD	Abstract, JP 55079268, "Laminated packaging material - comprising substrate, and resin layer comprising EVA copolymer and polymer of ethylene or alpha-olefin with unsatd. carboxylic acid", (09/02/93)	
	AE	Abstract, JP 2001207145, "Hotmelt adhesive composition that contains EVA resin, tackifier resin, and wax, exhibits excellent basic adhesive properties like dry adhesion strength and thermal stability, and can be suitably applied for paper packaging", (10/18/01)	
	AF	Abstract, JP 48001823, "Coating composition for heat-sticking", (01/20/73)	
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	AK	Abstract, Patel, R.M. et al., "Comparison of EVA and polyolefin plastomer as a blend component in various films applications", Polyolefins Research, The Dow Chemical Company, Freeport, TX; Polym., Laminations, Coat. Conf. (1997), Volume 1, pp. 239-242, (TAPPI Press, Atlanta, GA.)	
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	AB	Abstract, Vansant, J.D., "The effect of coextrusion on the hot-tack performance of a common ionomer resin", Chestnut Run Laboratories Packaging & Industrial Polymers, DuPont Company, Wilmington, DE; Polym., Laminations Coat. Conf. (1998), Vol. 2, pp. 743-754 (TAPPI Press, Atlanta, GA.)	
	AC	de Garavilla, J.R., "Ionomer, acid copolymer, and metallocene polyethylene resins: A comparative assessment of sealant performance", Vol. 78, No. 6, Tappi Journal, pp. 191-203 (June, 1995)	
	AD	Duncan et al., "EVA and VAE Copolymers for Hot Melt PSA's", Adhesives Age, (March, 1980), pp. 37-41	
	AE	McDonald, J.W., et al., "Factors Affecting Hot Tack in Hot Melt Systems Containing Ethylene Interpolymers", Tappi Journal, Vol. 51, No. 7, pp. 46A-50A (July, 1968)	
	AF	Rapra Abstract, "Eastman Builds in Polyolefins; Plans entry into LLDPE, HDPE Lists", Modern Plastics International 19, No. 9, (September, 1989), pp. 32-36	
	AG	Schmidt, et al., "Coatings & Laminates of Improved Ethylene Alkyl Acrylate Copolymer With Polypropylene and Polyester", TAPPI Proceedings, 1997 Polymers, Laminations & Coatings Conference, Vol. 2, pp. 397-415	
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U.S. PATENT DOCUMENTS

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	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	PUBL. DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
KE	AH	EP 0 957 147	11/17/99	Europe	C09J	123/00		
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	AK							
	AL							
	AM							
	AN							

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